FAIRCHILD SEMICONDUCTOR®

November 2013

# IRFNL210B

## N-Channel B-FET

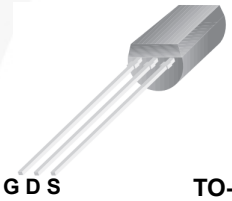
### 200 V, 1.0 A, 1.5 Ω

## Description

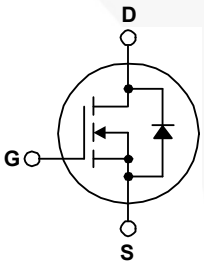
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supplies, DC-AC converters for uninterrupted power supply and motor control.

## Features

- 1.0 A, 200 V, $R_{DS(on)}$ = 1.5 Ω @ $V_{GS}$ = 10 V
- Low Gate Charge ( typical 7.2 nC)
- Low Crss ( typical 6.8 pF)
- Fast Switching
- 100% Avalanche Tested
- Improved dv/dt Capability




TO-92L




## Absolute Maximum Ratings $T_C$ = 25°C unless otherwise noted.

| Symbol | Parameter | | IRFNL210BTA_FP001 | Unit |
|---|---|---|---|---|
| $V_{DSS}$ | Drain-Source Voltage | | 200 | V |
| $I_D$ | Drain Current - Continuous ($T_C$ = 25°C) | | 1.0 | A |
| | - Continuous ($T_C$ = 100°C) | | 0.93 | A |
| $I_{DM}$ | Drain Current - Pulsed | (Note 1) | 10 | A |
| $V_{GSS}$ | Gate-Source Voltage | | ± 30 | V |
| $E_{AS}$ | Single Pulsed Avalanche Energy | (Note 2) | 40 | mJ |
| $I_{AR}$ | Avalanche Current | (Note 1) | 3.3 | A |
| $E_{AR}$ | Repetitive Avalanche Energy | (Note 1) | 0.031 | mJ |
| dv/dt | Peak Diode Recovery dv/dt | (Note 3) | 5.0 | V/ns |
| $P_D$ | Power Dissipation ($T_C$ = 25°C) | | 3.1 | W |
| | - Derate above 25°C | | 0.025 | W/°C |
| $T_J$, $T_{STG}$ | Operating and Storage Temperature Range | | -55 to +150 | °C |
| $T_L$ | Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds | | 300 | °C |

## Thermal Characteristics

| Symbol | Parameter | IRFNL210BTA_FP001 | Unit |
|---|---|---|---|
| $R_{\theta JL}$ | Thermal Resistance, Junction-to-Lead, Max. | 40 | °C/W |

## Package Marking and Ordering Information

| Part Number | Top Mark | Package | Packing Method | Reel Size | Tape Width | Quantity |
|---|---|---|---|---|---|---|
| IRFNL210BTA_FP001 | 210B | TO-92L | AMMO | N/A | N/A | 2000 units |

## Electrical Characteristics $T_C$ = 25°C unless otherwise noted.

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|---|---|---|---|---|---|---|
| **Off Characteristics** | | | | | | |
| $BV_{DSS}$ | Drain-Source Breakdown Voltage | $V_{GS}$ = 0 V, $I_D$ = 250 μA | 200 | -- | -- | V |
| $\Delta BV_{DSS}$ / $\Delta T_J$ | Breakdown Voltage Temperature Coefficient | $I_D$ = 250 μA, Referenced to 25°C | -- | 0.2 | -- | V/°C |
| $I_{DSS}$ | Zero Gate Voltage Drain Current | $V_{DS}$ = 200 V, $V_{GS}$ = 0 V | -- | -- | 10 | μA |
| | | $V_{DS}$ = 160 V, $T_C$ = 125°C | -- | -- | 100 | μA |
| $I_{GSSF}$ | Gate-Body Leakage Current, Forward | $V_{GS}$ = 30 V, $V_{DS}$ = 0 V | -- | -- | 100 | nA |
| $I_{GSSR}$ | Gate-Body Leakage Current, Reverse | $V_{GS}$ = -30 V, $V_{DS}$ = 0 V | -- | -- | -100 | nA |
| **On Characteristics** | | | | | | |
| $V_{GS(th)}$ | Gate Threshold Voltage | $V_{DS}$ = $V_{GS}$, $I_D$ = 250 μA | 2.0 | -- | 4.0 | V |
| $R_{DS(on)}$ | Static Drain-Source On-Resistance | $V_{GS}$ = 10 V, $I_D$ = 0.5 A | -- | 1.16 | 1.5 | Ω |
| $g_{FS}$ | Forward Transconductance | $V_{DS}$ = 40 V, $I_D$ = 1.0 A | -- | 2.4 | -- | S |
| **Dynamic Characteristics** | | | | | | |
| $C_{iss}$ | Input Capacitance | $V_{DS}$ = 25 V, $V_{GS}$ = 0 V, f = 1.0 MHz | -- | 175 | 225 | pF |
| $C_{oss}$ | Output Capacitance | | -- | 30 | 40 | pF |
| $C_{rss}$ | Reverse Transfer Capacitance | | -- | 6.8 | 9.0 | pF |
| **Switching Characteristics** | | | | | | |
| $t_{d(on)}$ | Turn-On Delay Time | $V_{DD}$ = 100 V, $I_D$ = 3.3 A, $R_G$ = 25 Ω (Note 4) | -- | 5.2 | 20 | ns |
| $t_r$ | Turn-On Rise Time | | -- | 35 | 80 | ns |
| $t_{d(off)}$ | Turn-Off Delay Time | | -- | 20 | 50 | ns |
| $t_f$ | Turn-Off Fall Time | | -- | 25 | 60 | ns |
| $Q_g$ | Total Gate Charge | $V_{DS}$ = 160 V, $I_D$ = 3.3 A, $V_{GS}$ = 10 V (Note 4) | -- | 7.2 | 9.3 | nC |
| $Q_{gs}$ | Gate-Source Charge | | -- | 1.3 | -- | nC |
| $Q_{gd}$ | Gate-Drain Charge | | -- | 3.5 | -- | nC |
| **Drain-Source Diode Characteristics and Maximum Ratings** | | | | | | |
| $I_S$ | Maximum Continuous Drain-Source Diode Forward Current | | -- | -- | 3.3 | A |
| $I_{SM}$ | Maximum Pulsed Drain-Source Diode Forward Current | | -- | -- | 10 | A |
| $V_{SD}$ | Drain-Source Diode Forward Voltage | $V_{GS}$ = 0 V, $I_S$ = 3.3 A | -- | -- | 1.5 | V |
| $t_{rr}$ | Reverse Recovery Time | $V_{GS}$ = 0 V, $I_S$ = 3.3 A, $dI_F$ / dt = 100 A/μs | -- | 106 | -- | ns |
| $Q_{rr}$ | Reverse Recovery Charge | | -- | 0.37 | -- | μC |

**Notes:**
1. Repetitive rating : pulse-width limited by maximum junction temperature.
2. L = 5.5 mH, $I_{AS}$ = 3.3 A, $V_{DD}$ = 50 V, $R_G$ = 25 Ω, Starting $T_J$ = 25°C.
3. $I_{SD} \leq$ 3.3 A, di/dt ≤ 300 A/μs, $V_{DD} \leq BV_{DSS}$, Starting $T_J$ = 25°C.
4. Essentially independent of operating temperature.

## Typical Characteristics

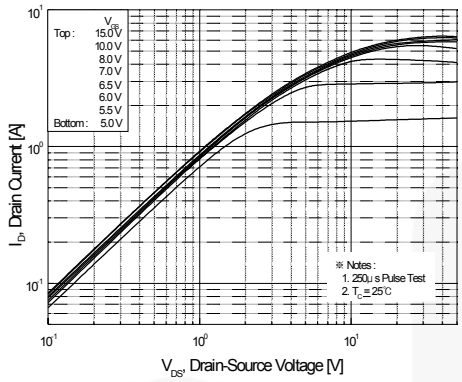



**Figure 1. On-Region Characteristics**

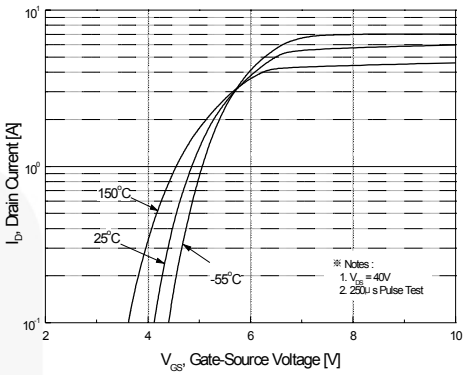



**Figure 2. Transfer Characteristics**

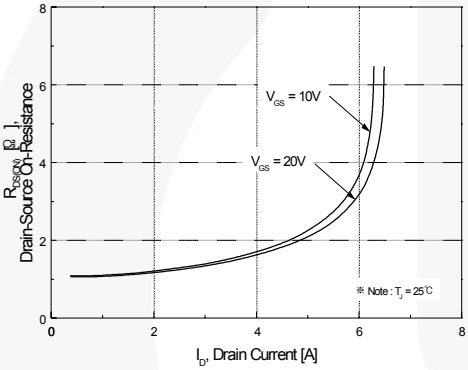



**Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage**

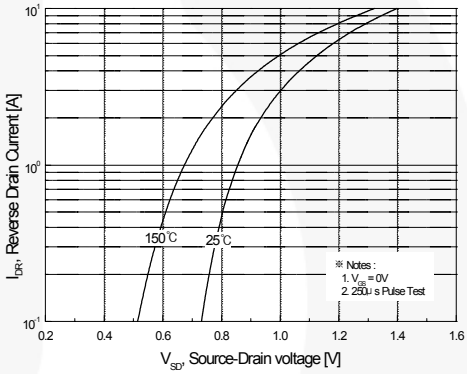



**Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature**

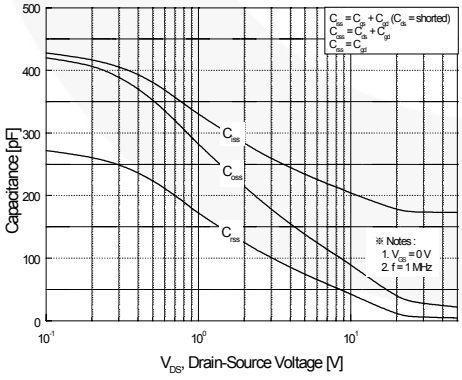



**Figure 5. Capacitance Characteristics**

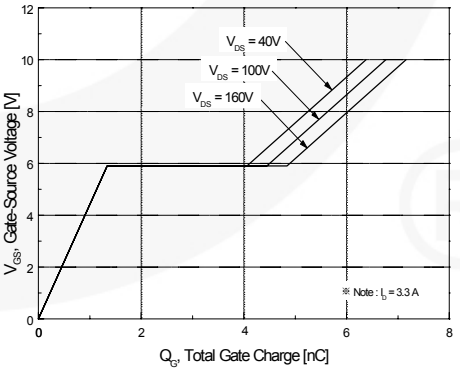



**Figure 6. Gate Charge Characteristics**

## Typical Characteristics (continued)

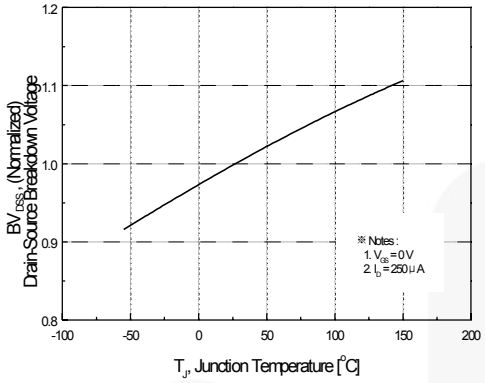



**Figure 7. Breakdown Voltage Variation**

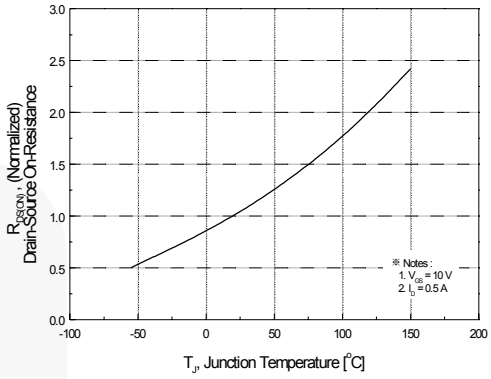



**Figure 8. On-Resistance Variation vs Temperature**

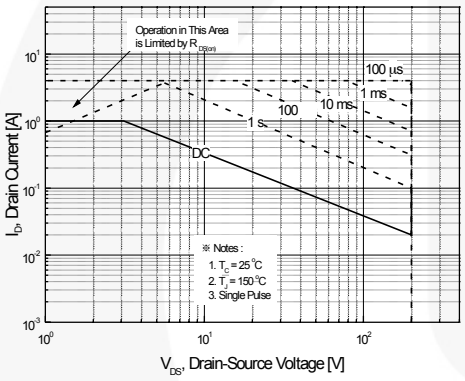



**Figure 9. Maximum Safe Operating Area**

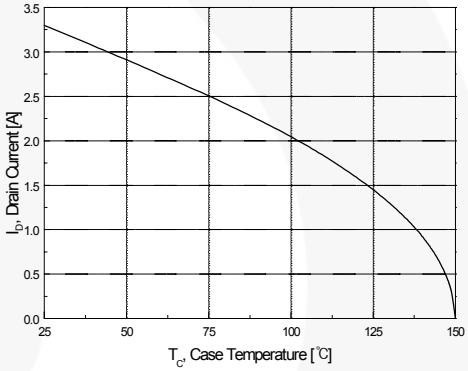



**Figure 10. Maximum Drain Current vs Case Temperature**

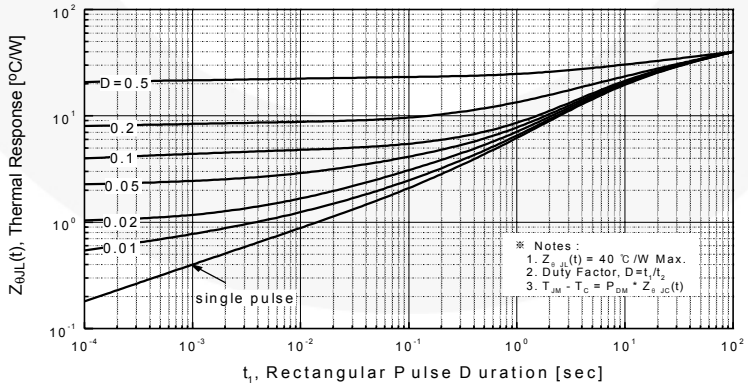



**Figure 11. Transient Thermal Response Curve**

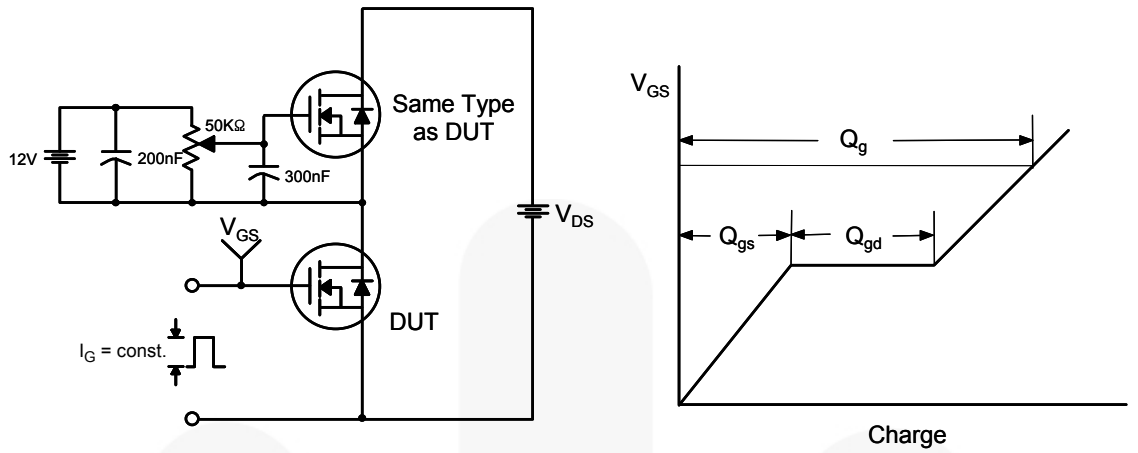



**Figure 12. Gate Charge Test Circuit & Waveform**

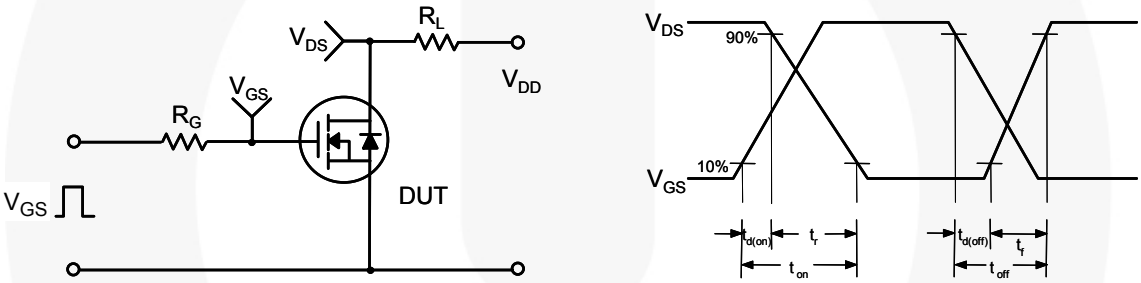



**Figure 13. Resistive Switching Test Circuit & Waveforms**

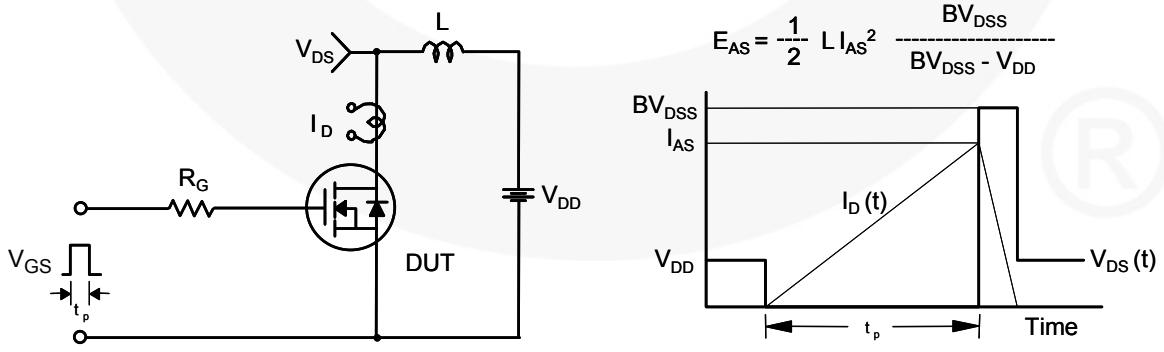



**Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms**

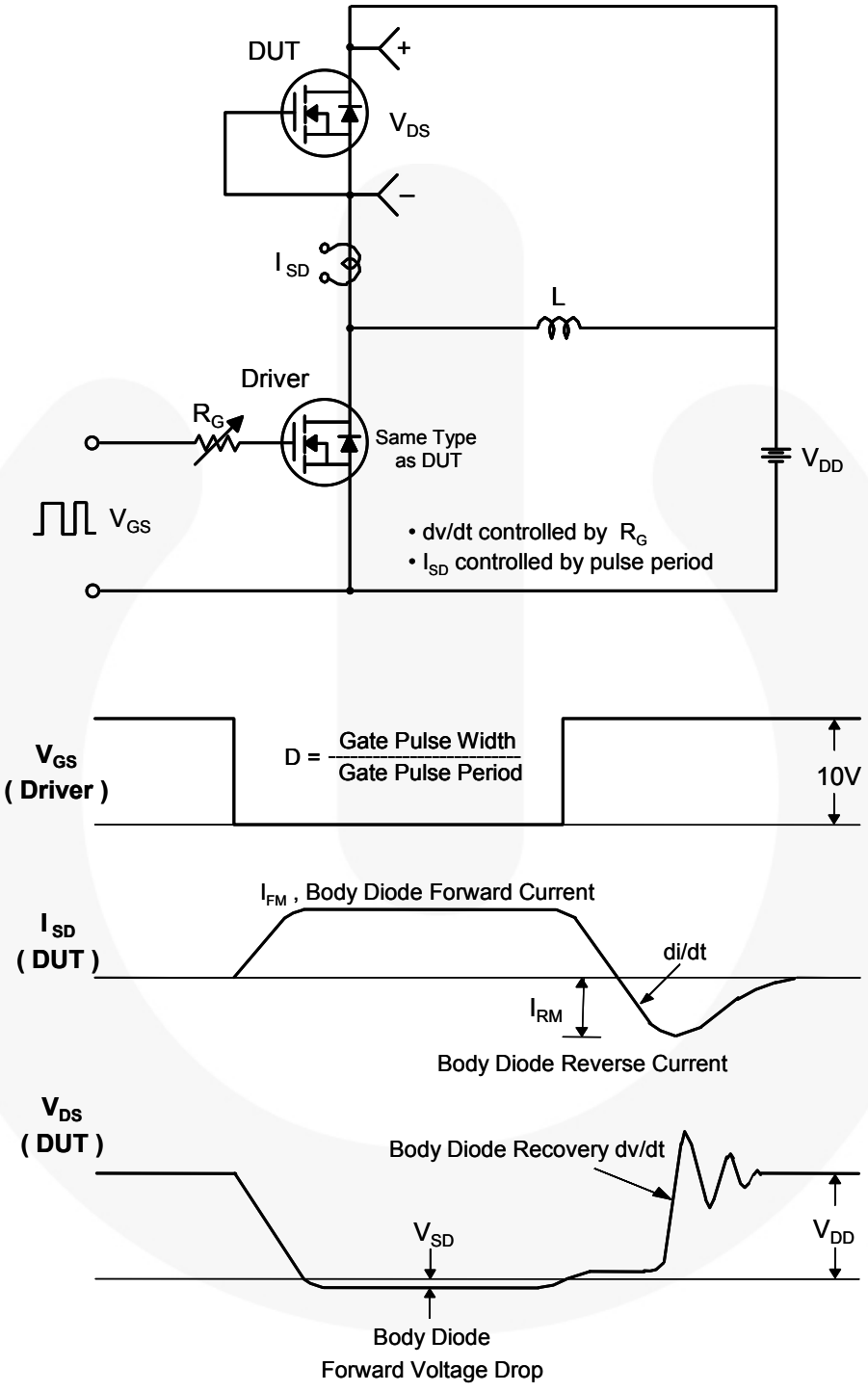



**Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms**

## Mechanical Dimensions

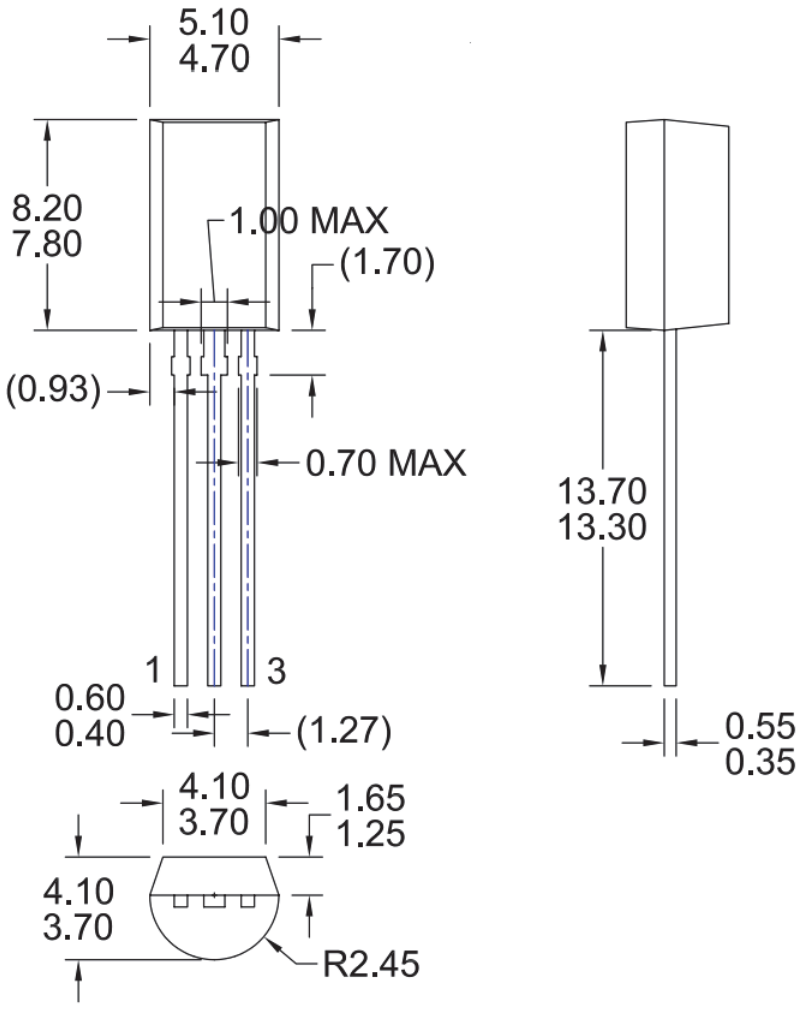



**Figure 16. TO92L, 3-Lead, 8 mm Long Body**

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